Semiconductor Wafers - FG for very soft and/or brittle parts

1156

Grinding

	Steps	PG	FG	FG 2	FG 3
Surface	Type	SiC Foil #500	SiC Foil #1200	SiC Foil #2000	SiC Foil #4000
	Disc speed (rpm)	150	150	150	150
Abrasive	Type				
	Predosing/dosing				
Lubricant	Type	Water	Water	Water	Water
	Predosing/dosing				
	Force (N)	20	20	20	20
	Holder direction	>>	>>	>>	>>
	Holder speed (rpm)	150	150	150	150
	Time (min)	1	1	1	1

Polishing

	Steps	DP	OP
Surface	Type	MD-Nap	MD-Chem
	Disc speed (rpm)	150	150
Abrasive	Type	DP-Susp. P 1 µm	OP-S, 0.25 µm
	Predosing/dosing	3/6	1/10
Lubricant	Type	DP-Blue	
	Predosing/dosing	3/14	
	Force (N)	30	10
	Holder direction	>>	><
	Holder speed (rpm)	150	150
	Time (min)	5	1

Method comments

The method is developed to fit a standard equipment configuration with 30 mm specimen on 300mm disc. Dosing levels are valid for following equipment: Tegramin, AbraPol and LaboPol

For advice on how to adjust the method to fit your equipment, please take a look at Preparation Parameters.

The preparation time for the plane grinding (PG) step depends very much on the condition of the samples and if they are prepared as single specimens or clamped in a specimen holder. Please check the samples after the first step and repeat it if necessary.

Take a look at Preparation Parameters